




Full Material Declaration for attached parts list

Report generated: 08 February 2024, 15:33 GMT



Diotec Semiconductor AG

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Declarations authorised by:

Udo Steinebrunner, Product Manager, -

Declaration effective from: 01 January 2016 [Approved on 08 February 2024, 15:31 GMT]

Materials and substances

Use/Location	Material Group	% w/w of material in the part	Substances in the material	CAS Number	% w/w of substance in the material
Chip (die)	Other inorganic materials	1.9%	Nickel REACH Article 67 Exemption	7440-02-0	1%
			Diboric acid, lead(2+) salt (1:2); Lead borate Exempt from other regulatory requirements EU RoHS Exemption 7(c)-I Exempt from other regulatory requirements	13703-85-0	5%
			Gold	7440-57-5	11.5%
			Silicon oxide	11126-22-0	20%
			Silicon	7440-21-3	62.5%
Die attach	Lead and Lead alloys	0.4%	Silver	7440-22-4	2.5%
			Tin	7440-31-5	5%
			Lead EU RoHS Exemption 7(a) Exempt from other regulatory requirements Exempt from other regulatory requirements	7439-92-1	92.5%
Encapsulation	EP (Epoxy resin)	51.4%	Carbon black	1333-86-4	0.3%
			ANTIMONY TRIOXIDE Exempt from other regulatory requirements	1309-64-4	0.8%
			3,5,3',5'- TETRABROMOBISPHENOL A Exempt from other regulatory requirements	79-94-7	0.99%

Use/Location	Material Group	% w/w of material in the part	Substances in the material	CAS Number	% w/w of substance in the material
Leadfinish Leadframe	Tin plating Copper (e.g. copper amounts in cable harnesses)	1.7%	Epoxy resin 89	26335-32-0	27.61%
			Quartz sand	60676-86-0	70.3%
		44.6%	Tin	7440-31-5	100%
			Copper	7440-50-8	100%

Attached parts list

Part number	Part name	Part Mass	Part Mass UoM
DO-214AC/SMA-GP	DO-214AC/SMA-GP	0.07	g